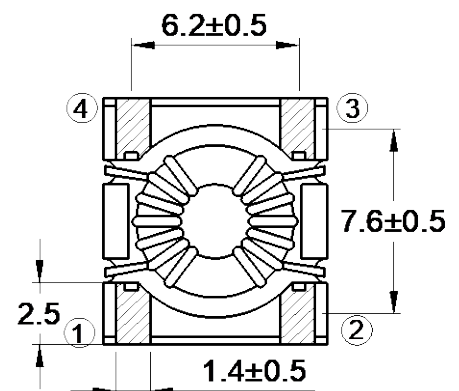
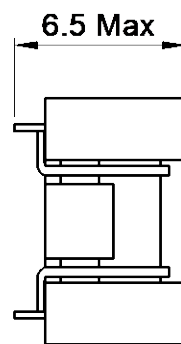
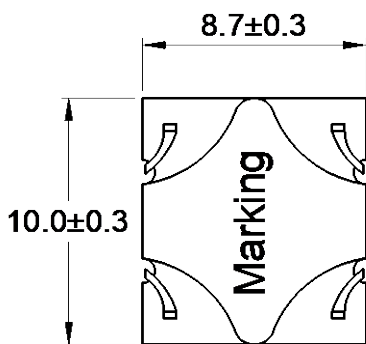




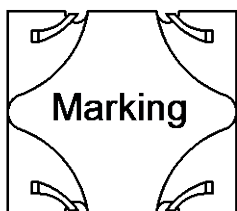
### Outline: 产品概要

- Excellent impedance characteristics, making it great for suppressing common mode noise.  
高阻抗特性，能高效抑制共模噪音效果。
- Low profile design makes it optimal for surface mounting.  
较低的高度设计，适合表面安装。
- Measures against common mode noise in power lines for various DC power lines, multimedia devices, and various electronic devices, including automotive power trains.  
各种电子产品、多媒体设备，包括车载动力传递的 DC 电源线的共模噪音抑制。
- Operating temperature :  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$   
(Including coil's temperature rise)  
工作温度:  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$  (包含线圈发热)

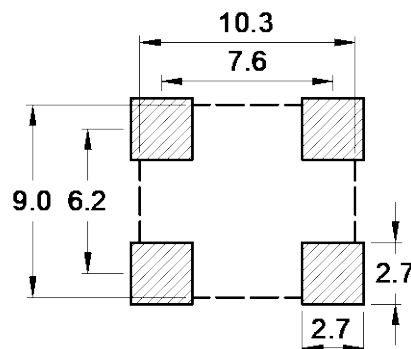
### 1 Appearance and Dimensions (mm) 外形尺寸 (mm)



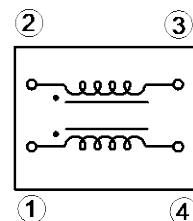
### 2 Marking 印字标识



### 3 Reference Land Pattern (mm) 参考基板尺寸 (mm)



### 4 Schematic 原理图



## 5 Electrical Characteristics 电气特性

Part No. 型号	Inductance (mH) 电感值	Impedance (Ω) 阻抗值※1	Leakage Inductance (nH) 漏感※2	D.C.R (mΩ) 直流电阻	Rated Current (A) 额定电流※3	Rated Voltage (V) 额定电压	Frequency Range (MHz) 频率范围
		Min	Typical	Max	Max	Max	
CSTR1060-202	2.00±40%	2,100	220	290	0.75	80.0	0.50~15.0
CSTR1060-302	3.00±40%	3,200	330	330	0.65	80.0	0.50~10.0
CSTR1060-402	4.00±40%	4,200	450	550	0.52	80.0	0.50~5.00
CSTR1060-502	5.00±40%	5,300	650	680	0.35	80.0	0.50~3.00

■ All data is tested based on 25°C ambient temperature.  
所有数据基于环境温度 25°C条件下测试。

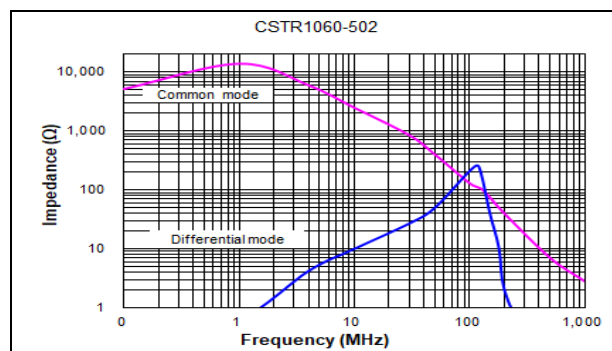
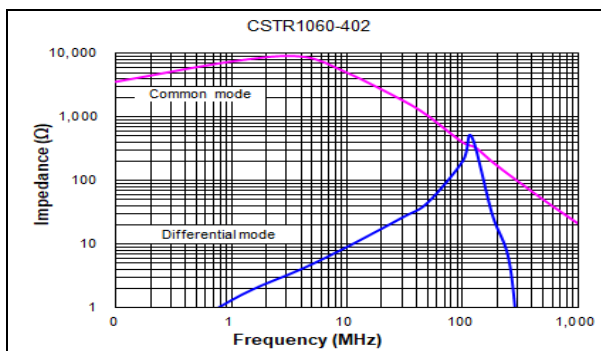
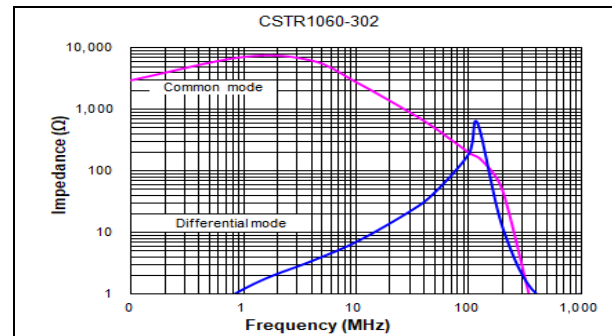
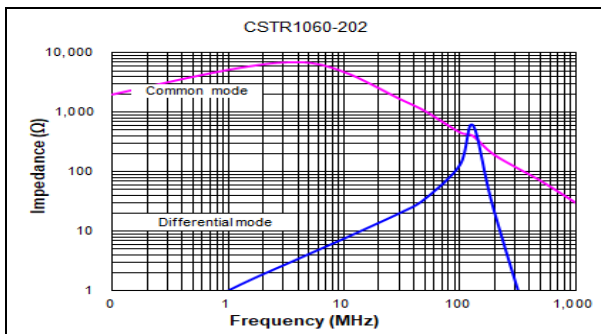
※1 Impedance measure condition reference frequency range.  
共模阻抗测试条件参考频率范围。

※2 Leakage inductance is for L1 and is measured with L2 shorted.  
漏感：在短路 L2 绕组的前提下测试 L1 绕组所得的电感。

※3 Rated current: the value of DC current when the temperature rise is  $\Delta T40^{\circ}\text{C}$  ( $T_a=25^{\circ}\text{C}$ ).  
额定电流：使产品温度上升到  $\Delta T40^{\circ}\text{C}$ 时所加载的直流电流值( $T_a=25^{\circ}\text{C}$ )。

※ Special remind: Circuit design, component placement, PCB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.  
特别提醒：线路设计，组件布局，印刷线路板(PCB)尺寸及厚度，散热系统等均会影响产品温度。请务必在最终应用时，验证产品发热状况。

## 6 Impedance vs Frequency Curve 阻抗值 VS 频率曲线

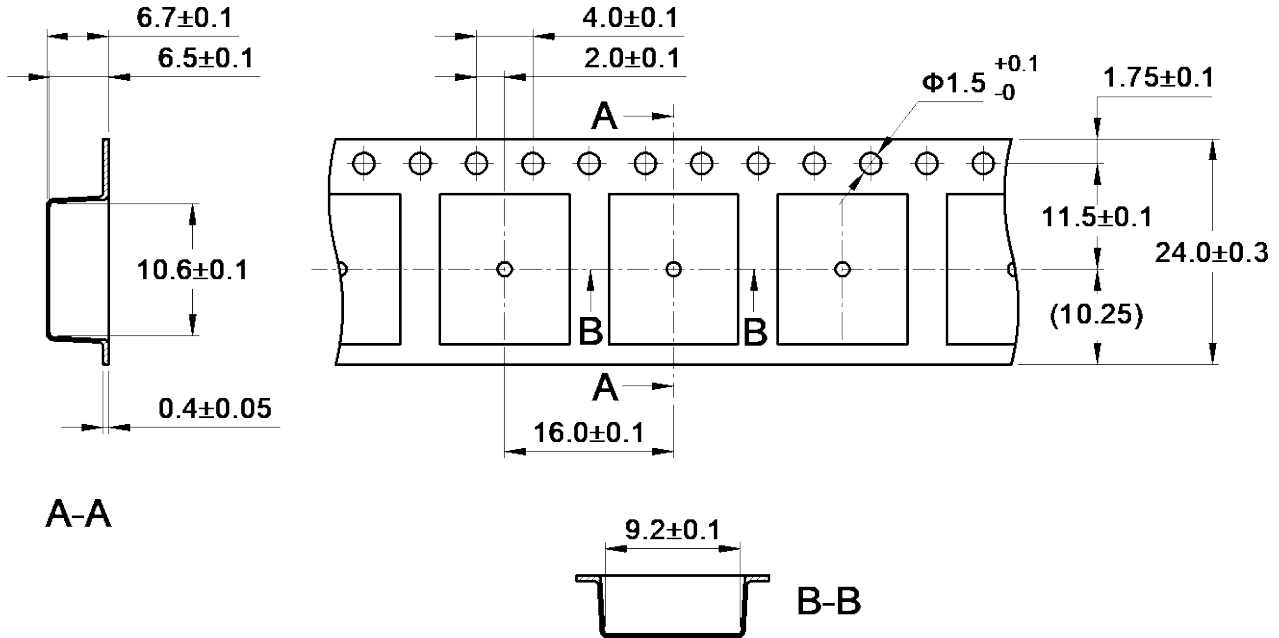


**7 Packing Specification**

**包装规格**

**7.1 Carrier Tape Dimensions (mm)**

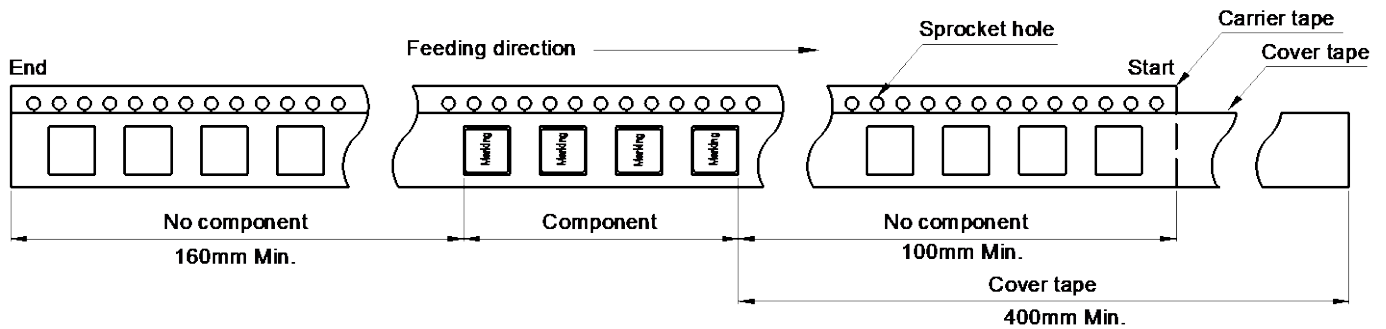
**载带尺寸**



※ Packing is referred to the international standard IEC 60286-3.  
包装参照国际标准 IEC 60286-3。

**7.2 Tape Direction**

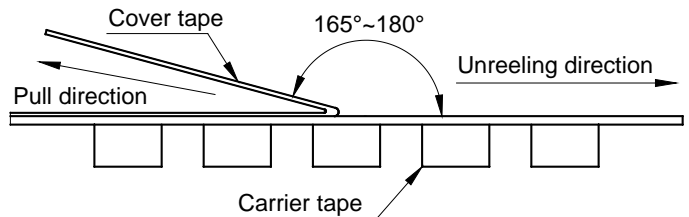
**捆包方向**



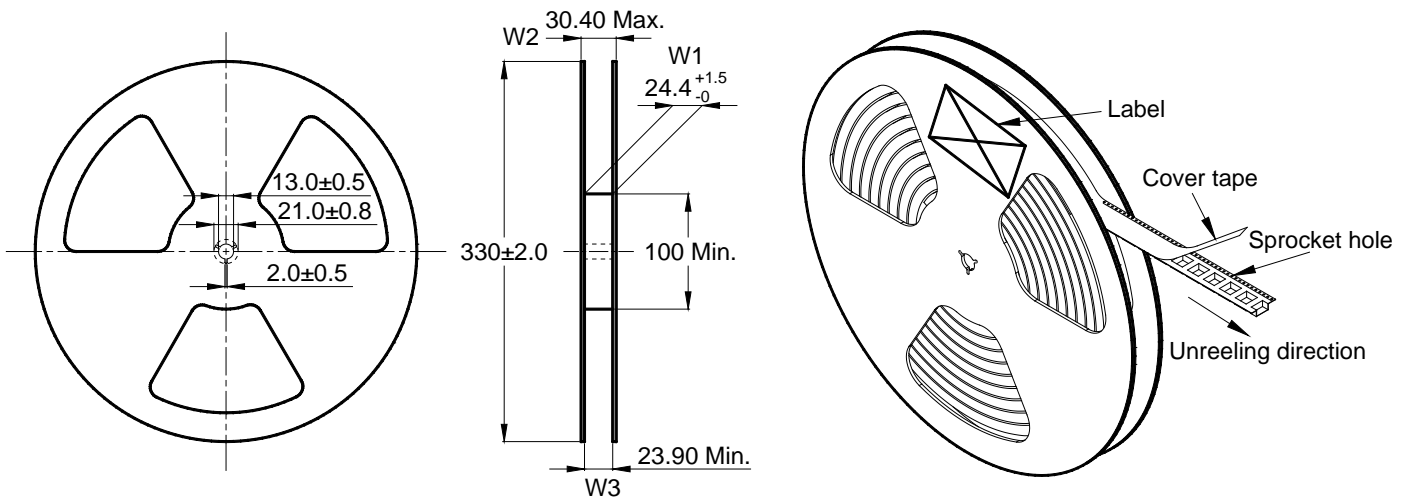
**7.3 Cover Tape Peel Off Condition**

**盖带剥离条件**

- Cover tape peel force shall be 0.1 to 1.3N.  
盖带剥离力度为 0.1~1.3N。
- Reference peel speed  $300 \pm 10\text{mm/min.}$   
参考剥离速度  $300 \pm 10\text{mm/分钟}$ 。



## 7.4 Reel Dimensions (mm) 卷盘尺寸(mm)



## 7.5 Carton Dimensions and Packing Quantity 包装箱尺寸和包装数量

■ Inner Carton: 340×340×95mm  
内包装盒

■ Out Carton : 355×355×385mm  
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
CSTR1060	500pcs	(500×2) = 1000pcs	(1000×3) = 3000pcs

## 7.6 Label Making 标签标识

The following items will be marked on the tray of product label and shipping label.  
以下项目将明确标识于产品吸塑盘标签以及运输标签上。

Production Label 产品标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

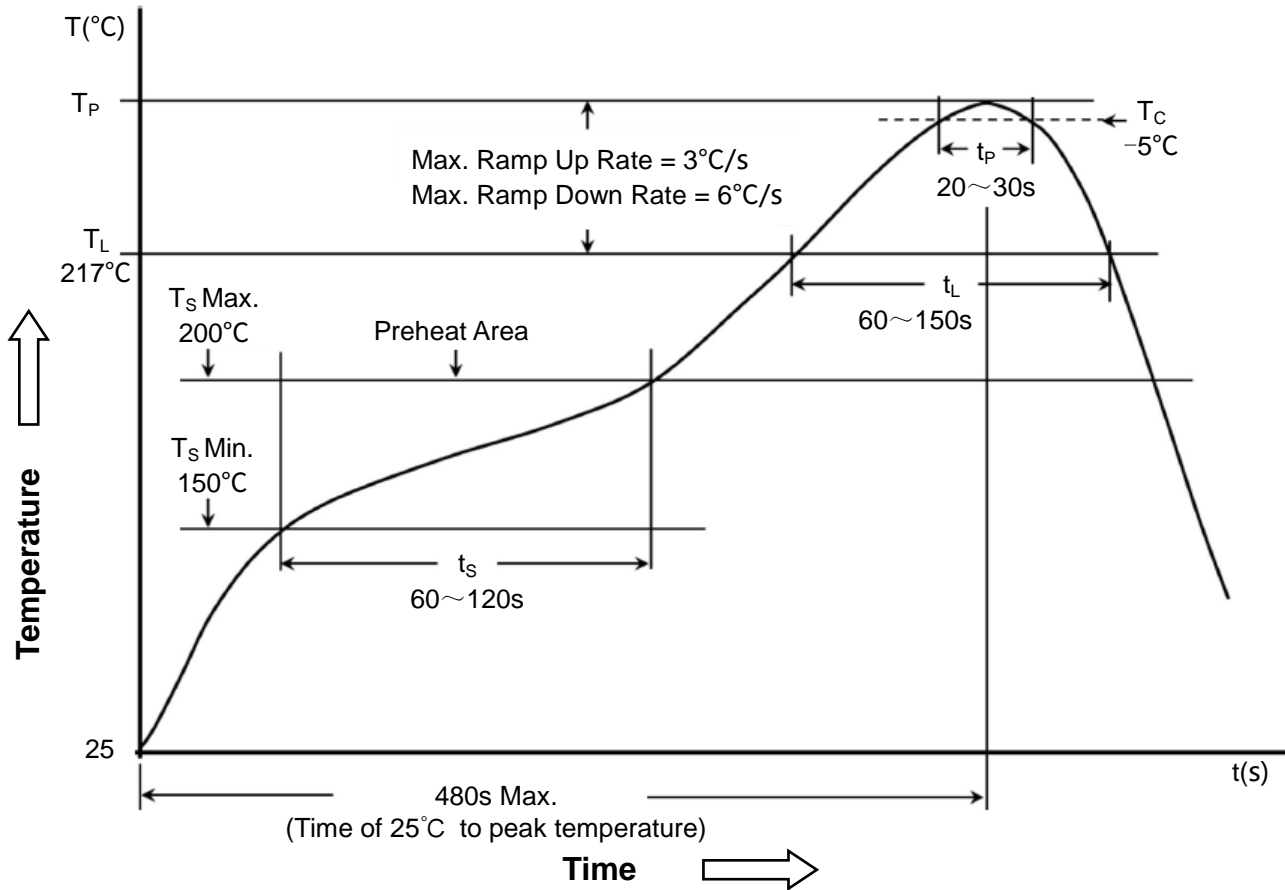
Shipping Label 运输标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

**8 Soldering Specification**

**焊接规格**

**8.1 Reflow Profile for SMT Components**

SMT 回流焊温度曲线



**8.2 Classification of Peak Package Body Temperature (Tp)**

封装体峰值温度(Tp)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm <sup>3</sup>	350~2000 mm <sup>3</sup>	>2000 mm <sup>3</sup>
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.

回流焊参照标准 IPC/JEDEC J-STD-020D.